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(54) **SERVER WITH HYBRID THERMAL
MANAGEMENT SYSTEM**

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(71) Applicant: **Carrier Corporation**, Palm Beach
Gardens, FL (US)

(72) Inventors: **Arindom Joardar**, Jamesville, NY
(US); **Richard Lord**, Monteagle, TN
(US); **Michel Grabon**, Bressolles (FR);
Tobias Sienel, Baldwinsville, NY (US);
My Dinh Truong, Redwood City, CA
(US); **Tikhon Suresh Pichai**,
Simpsonville, SC (US)

(57) **ABSTRACT**

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A method of cooling an assembly including at least one
heat-generating electronic device and at least one peripheral
heat-generating device includes cooling the at least one
heat-generating electronic device with a primary cooling
fluid and cooling the at least one heat-generating electronic
device and the at least one peripheral heat-generating device
with a secondary cooling fluid. The secondary cooling fluid
is distinct from the primary cooling fluid.

